

**AMENDMENTS TO THE SPECIFICATION:**

**Please amend the paragraph under "Technical Field" on page 1  
according to the following:**

The invention pertains to the field of power semiconductor engineering and is based on a power semiconductor module. ~~module according to the preamble of Claim 1.~~

**Please amend the paragraph under "Description of the Invention" on  
page 3 according to the following:**

The invention is based on the objective of disclosing a power semiconductor module, the housing of which has a significant elastic deformability and can be very easily manufactured with respect to the process technology. ~~This objective is attained with the characteristics of Claim 1. Advantageous additional developments of the invention are disclosed in the dependent claims.~~